SHEET FOR PROTECTING SURFACE OF SEMICONDUCTOR WAFER, SEMICONDUCTOR DEVICE MANUFACTURING METHOD AND SEMICONDUCTOR WAFER PROTECTION METHOD USING SHEET

Abstract

To provide a semiconductor wafer surface protection sheet having good adhesion to irregularities on a patterned surface of a semiconductor wafer, and having good peelability after wafer grinding. Specifically, a semiconductor wafer surface protection sheet is provided that includes a base layer having a tensile elasticity at 25˚C, E_A (25), of 1 Gpa or more; a resin layer A that satisfies the condition E_A (60) / E_A (25) < 0.1, where E_A (25) is a tensile elasticity at 25˚C and where E_A (60) is a tensile elasticity at 60˚C, the E_A (60) ranging from 0.005 MPa to 1 MPa; and a resin layer (B) having a tensile elasticity at 60˚C, E_B (60), of 1 Mpa or more and having a thickness of 0.1 μm to less than 100 μm, the E_B (60) being larger that E_A (60) of the resin layer A.

Figure 1